



FLEXTURA® CLUSTER
WHEN THIN FILM MATTERS

FLEXTURA® 200 CLUSTER

The Flextura® Cluster platform is probably the most flexible 200mm cluster tool available. It is truly almost Plug&Play and you may add process modules as your need for capacity or new processes increase.

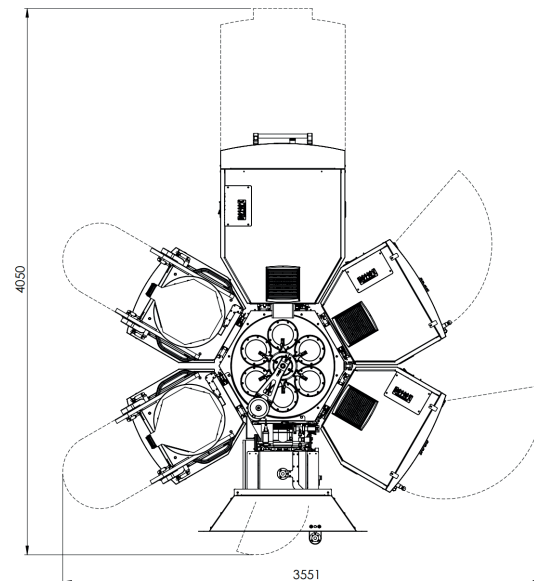
The Flextura® way of thinking is giving you the possibility to let the capital investment follow the increasing demands of your facility.

PROCESS MODULES

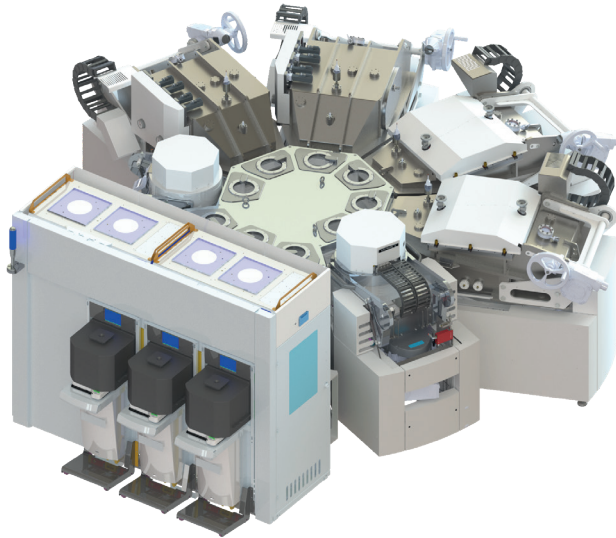
- Direct magnetron sputtering (DC, RF, pDC, and HiPIMS)
- Multi magnetron chamber (co-sputtering)
- Automated glancing angle deposition on 200mm wafers
- E-beam evaporation
- Remote Plasma Sputtering technology
- RF/ICP etch, degas, cooling, alignment
- Single wafer or batch processing directly from cassette-to-cassette

PLATFORM HIGHLIGHTS

- Six-port transfer module with Brooks Magnatran LEAP Robot
- Single or dual cassette load locks
- Wafer mapping, cross-slot detection, alignment
- Substrate heating up to 1000°C
- Dynamic in-situ feedback control by PEM or RGA in reactive sputtering
- Electrostatic chuck (ESC) with backside gas for substrate cooling or heating, RF/DC bias option
- P-chuck – pneumatic chuck with edge clamp
- SECS/GEM, Direct SQL server logging
- Market leading process software technology for accurate real time control of deposition
- Bridge tool – from R&D to 200mm wafers – standard SEMI or custom cassette



FLEXTURA® 300 CLUSTER



Introducing the Flextura® 300 Cluster tool - building on the expertise gained from our Flextura® 200 Cluster, this highly reliable PVD platform is an excellent choice for deposition of metals, oxides, and nitrides to produce high quality thin films.

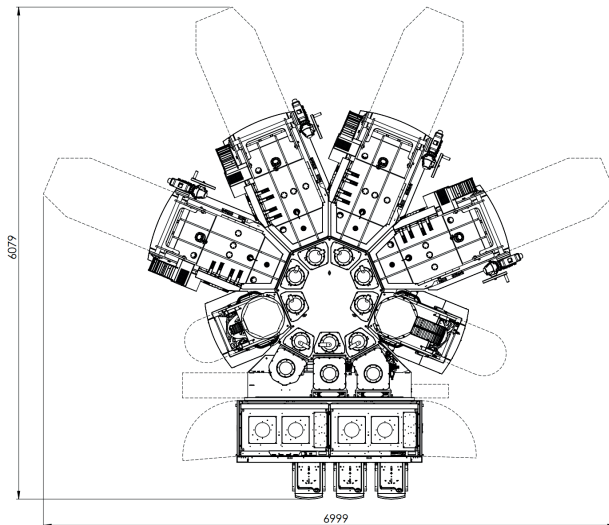
Including degas, pre-clean, and PVD modules and utilising the flexibility of the Flextura® platform, the Flextura® 300 Cluster allows customer to optimise the configuration to best fit their applications.

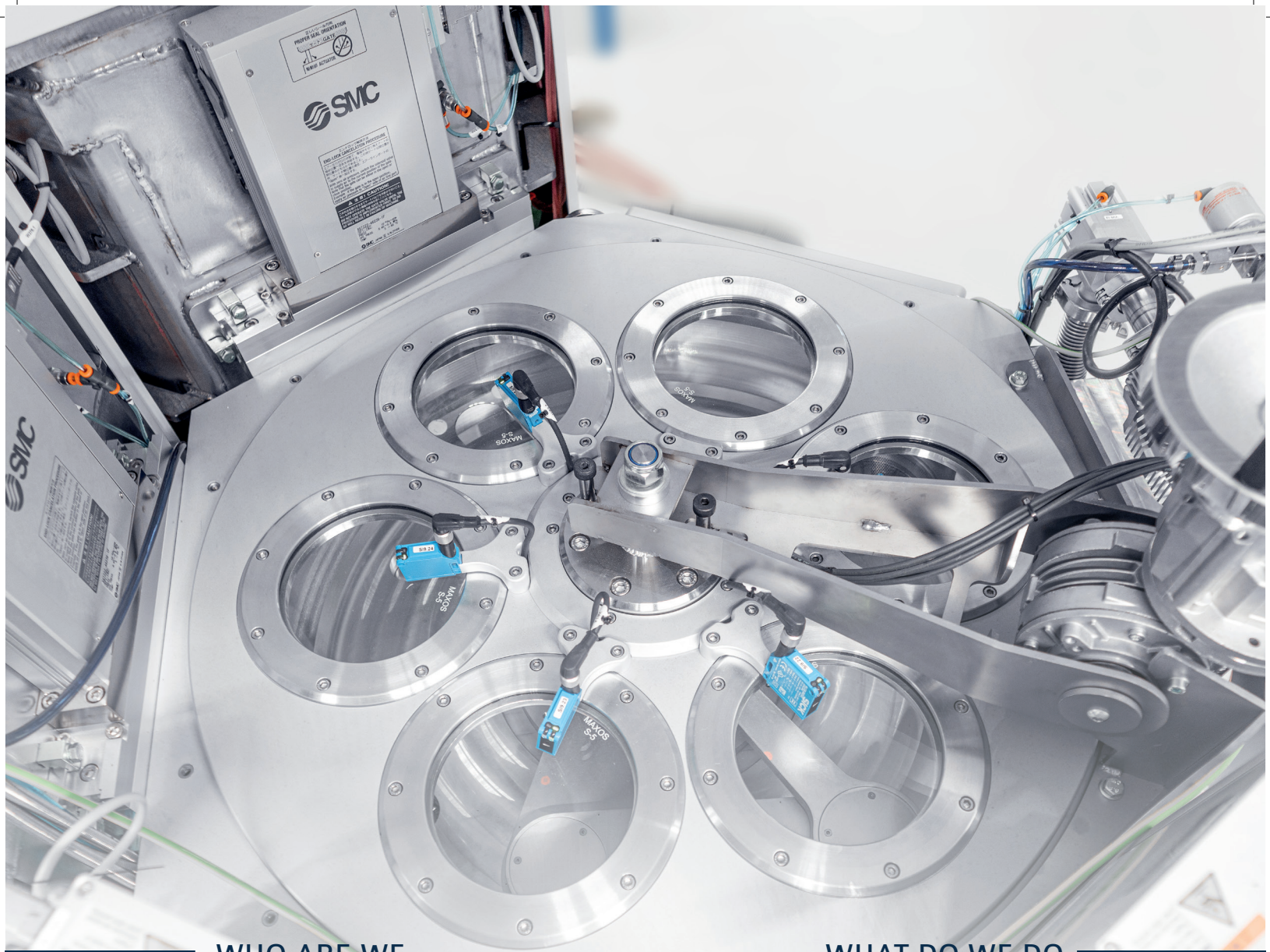
PROCESS MODULES

- Direct magnetron sputtering (DC, RF, and pDC)
- Linear magnetron sputtering
- Multi magnetron chamber (co-sputtering)
- Degas, RF/ICP etch, cooling, alignment, buffer station
- Evaporation modules

PLATFORM HIGHLIGHTS

- Atmospheric front-end with Brooks JCP EFEM
- Up to four Vision™ Leap load ports supporting 300mm FOUPs or 200mm cassettes
- Substrate heating up to 950°C
- Wafer aligner, wafer mapping, cross-slot detection
- Transfer module with proven reliable wafer handling by Brooks Magnatron LEAP dual arm robot for maximum throughput and reliability
- Up to 6 process modules
- SECS/GEM compliant communication





WHO ARE WE

Polyteknik AS is a PVD equipment manufacturer with an innovative and best service approach. With more than 25 years in business, a global reference list, and an excellent platform of technology, Polyteknik AS has turned to be an appreciated partner in the thin film industry.

WHAT DO WE DO

The portfolio of platform systems ranges from small scale R&D to high volume or large area deposition systems. Polyteknik AS covers several deposition processes including sputtering, evaporation, and varieties of these. At Polyteknik AS you will meet a dedicated team interested in a strong co-operation towards the best solution.

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